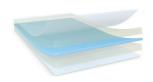


# 8694

## 제품 정보



## 100µm translucent light curable structural bonding tape

#### 제품 설명

테사 tesa® L-tape 8694 is a translucent light curable structural bonding tape. The curing process starts upon exposure to light. tesa® L-tape can be activated by light at a wavelength of 365 nm or 460 nm. Before curing tesa® L-tape has initial tack for easy pre-lamination. After activation there is an open time in which the substrates can be bonded. Thus, bonding of translucent and opaque substrates is possible. tesa® L-tape comes with immediate bonding strength which makes additional fixation after bonding unnecessary.

### 특성

- · High bonding performance, even on small bonding areas and thin design gaps
- · Tacky at room temperature
- · Bonding of translucent or opaque substrates
- · Immediate bonding strength after activation
- · The PET backing facilitates the die-cutting process

## **Applications**

tesa<sup>®</sup> L-tape is especially recommended for bonding of various substrates and components inside electronic devices which are sensitive to processing temperatures:

- · Bonding of temperature sensitive substrates
- · Component mounting in electronic devices

#### Technical Information (average values)

The values in this section should be considered representative or typical only and should not be used for specification purposes.

#### 제품 구조

•	기재 소재	PET	•	총두께	100 µm
•	점착제 종류	자외선 경화	•	컬러	반투명
•	이형지 종류	PET			

#### 제품군

•	Available colors	반투명	<ul> <li>Available thicknesses</li> </ul>	50, 100, 200
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## 속성 / 성능 값

•	인장강도 Activation temperature DuPont Push-out z-축 방향 접촉저항 (2kg)	_NULL N/cm 25 °C _NULL J _NULL N/cm NULL mOhm	•	테이프 수명 (포장상태) 테이프 수명 (포장상태) < 15°C 테이프 수명 (포장상태) < 5°C 테이프 수명 < 15°C 테이프 수명 < 25°C	_NULL months _NULL months _NULL months _NULL months NULL months
	전착력	10 N/mm <sup>2</sup>		테이프 수명 < 5°C	NULL months
	 점착력 (동적 전단)	10 N/mm²		표면 저항 x-y-축 방향	_NULL mOhm
•	점착력 (푸쉬 아웃)	6.3 N/mm <sup>2</sup>			

## 추가정보

tesa<sup>®</sup> L-tape is a reactive adhesive. It is activated by light at a wavelength of 365 nm or 460 nm. tesa<sup>®</sup> L-tape can be used for bonding of translucent or opaque substrates.

#### Bonding of opaque substrates

The open time of tesa<sup>®</sup> L-tape enables the bonding of opaque substrates like plastics and metals. tesa<sup>®</sup> L-tape can be activated by light as an die-cut or already pre-laminated onto the first substrate.

Activation of pre-laminated parts: First remove the covering liner of tesa<sup>®</sup> L-tape and pre-laminate the tape onto the first substrate. The pre-laminated parts are then exposed to light. The second substrate is bonded by applying sufficient pressure (≥3 bar) within 5 min after activation.

Activation of die-cuts: First the die-cut of tesa® L-tape is activated by light. The covering liner of the die-cut must be light-permeable (e.g., clear PET) to enable the activation of the tape. After activation the die-cut is pre-laminated onto the first substrate. The second substrate is then bonded by applying sufficient pressure (≥3 bar). Pre-lamination and bonding must take place within 5 min after activation.

#### Bonding of translucent substrates

Translucent substrates such as clear plastics can be bonded before activation by light. At least one substrate must be light-permeable to enable the activation of tesa<sup>®</sup> L-tape. First remove the covering liner of tesa<sup>®</sup> L-tape and pre-laminate the tape onto the first substrate. The second substrate is then bonded by applying sufficient pressure (≥3 bar). The bonded parts are then exposed to light to start curing of the adhesive.

#### Pre-lamination conditions

Before curing tesa<sup>®</sup> L-tape has initial tack and can be pre-laminated like a common PSA tape A pressure of ≥1 bar should be applied to ensure proper wet-out to the surface

#### Bonding and curing conditions

- Light source: Lamp of 365 nm or 460nm
- Light dose: 20 50 J/cm² at 365 nm or 30 60 J/cm² at 460nm



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### 추가정보

Activation time: ≥30 s
Pressure: ≥3 bar
Bonding time: ≥30 s

Bonding strength values were obtained under standard laboratory conditions. (Material: PC test specimen / bonding conditions: Light dose: 52 J/cm² at 460 nm; activation time: 45 s; pressure: 5 bar for 30 s). To reach maximum bonding strength surfaces should be clean and dry.

## 공지사항

테사에서 판매하는 제품들은 엄격한 품질관리를 통해 생산되고 있으며, 테사에서 제공하는 전문적인 정보들은 오랜기간의 경험을 기반으로 하고 있습니다. 관련 정보는 평균값에 근거하며, 특별한 용도에는 적합하지 않을 수 있습니다. tesa SE는 관련 정보의 명시적 또는 암묵적인 보증을 하는 것은 아니며, 이는 특별한 용도에 적합성 또는 상업성과 관련한 어떠한 암묵적인 보증도 포함하지 않습니다. 사용자는 제품을 사용하기 전에 적용부위에 적합한지를 검토하시기 바라며, 기타문의사항이 있으시면 저희 직원에게 문의 바랍니다

